Topotactic Phase Transition Driving Memristive Behavior

Venkata R. Nallagatla, Thomas Heisig, Christoph Baeumer, Vitaliy Feyer, Matteo Jugovac, Giovanni Zamborlini, Claus M. Schneider, Rainer Waser, Miyoung Kim, Chang Uk Jung,* and Regina Dittmann*

Redox-based memristive devices are one of the most attractive candidates for future nonvolatile memory applications and neuromorphic circuits, and their performance is determined by redox processes and the corresponding oxygen-ion dynamics. In this regard, brownmillerite SrFeO$_{2.5}$ has been recently introduced as a novel material platform due to its exceptional oxygen-ion transport properties for resistive-switching memory devices. However, the underlying redox processes that give rise to resistive switching remain poorly understood. By using X-ray absorption spectromicroscopy, it is demonstrated that the reversible redox-based topotactic phase transition between the insulating brownmillerite phase, SrFeO$_{2.5}$, and the conductive perovskite phase, SrFeO$_{3}$, gives rise to the resistive-switching properties of SrFeO$_x$ memristive devices. Furthermore, it is found that the electric-field-induced phase transition spreads over a large area in (001) oriented SrFeO$_{2.5}$ devices, where oxygen vacancy channels are ordered along the in-plane direction of the device. In contrast, (111)-grown SrFeO$_{2.5}$ devices with out-of-plane oriented oxygen vacancy channels, reaching from the bottom to the top electrode, show a localized phase transition. These findings provide detailed insight into the resistive-switching mechanism in SrFeO$_x$-based memristive devices within the framework of metal–insulator topotactic phase transitions.

As the traditional semiconductor manufacturing technology is approaching its physical limits for downscaling, novel material platforms and new modalities of operation are needed for the development of next-generation electronic devices.[1,2] In this context, resistive-switching random access memory (ReRAM) has emerged as one of the most promising candidates for future nonvolatile memory applications and neuromorphic circuits.[3–6] Resistive-switching devices consist of a metal–insulator–metal structure, which can be set to a conductive low resistance state (LRS) and reset to an insulating high resistance state (HRS) under application of an electric field.[7,8] The underlying mechanism driving the resistance change in transition metal oxide (TMO) based memristive devices is believed to be a nanoscale redox reaction, induced by oxygen-ion migration within so-called conductive filaments or at the electrode/oxide interface.[9–12] Accordingly, the oxygen-ion transport properties of the switching TMO layer play a decisive role for the device performance.[7,8] Besides conventional resistive-switching oxides such as Ta$_2$O$_{5-x}$ or HfO$_{2-x}$, strongly correlated electron TMOs have attracted great attention due to their rich electronic phases and the ability to control these electronic phases by a multitude of external stimuli.[2,14–18]
SrFeO$_{2.5}$ was determined to be the effective charge transfer energy $\Delta_{eff}$, which is responsible for the metallic behavior in PV-SrFeO$_3$.$^{[14,15]}$ The realization of a reversible TPT in BM-SrFeO$_{2.5}$ by the application of an external electrical field therefore presents an attractive route for optimizing the redox and resistive-switching characteristics of ReRAM devices.

Recently, we have successfully integrated epitaxial BM-SrFeO$_{2.5}$ thin films in a two-terminal memristive device and demonstrated a reliable resistive-switching performance, including high uniformity in the key switching characteristics (cycle-to-cycle and device-to-device variability).$^{[16]}$ Device endurances of >$10^6$ cycles combined with fast switching speeds ($\approx$10 ns) were achieved by engineering oxygen vacancy channels (OVCs) in a way that they connect bottom electrode (BE) and top electrode (TE).$^{[17]}$ We proposed a switching model that is based on the formation and rupture of conducting filaments caused by local TPT between the BM and PV phase in the SrFeO$_3$ active layer. While this model could qualitatively explain the observed switching characteristic, experimental evidence and a detailed microscopic understanding of the physicochemical processes are still missing. For a proper realization of TPT and the corresponding metal-insulator transition (MIT) in SrFeO$_3$ devices, it is essential to understand local changes of the electronic and chemical structure induced by redox switching process. Obtaining information about the concentration and diffusion of lattice oxygen ions and the valence state of Fe ions on the nanoscale might lead to a deeper understanding and ways to control the topotactic redox reaction.

In this communication, we demonstrate that a reversible TPT is indeed the underlying mechanism giving rise to the resistive-switching phenomena in BM-SrFeO$_{2.5}$ memristive devices. The different resistive states of the device are identified by measuring local O K-edge absorption spectra (XAS) using a photoemission electron microscope (PEEM). Spectromicroscopic investigations of the actively switching region showed a large population of oxygen 2p (ligand) holes. These changes in the electronic structure are caused by a phase transition between the insulating BM-SrFeO$_{2.5}$ and the conductive PV-SrFeO$_{3-\delta}$ ($\delta < 0.5$) phase. Furthermore, we explored the difference in the filament formation induced by in- and out-of-plane ordered oxygen vacancy channels by growing epitaxial BM-SrFeO$_{2.5}$ thin films with different crystallographic orientations. These findings provide a comprehensive understanding of resistive-switching processes in the BM SrFeO$_{2.5}$ memristive devices within the framework of metal-insultating TPT.

Resistive-switching Au/SrFeO$_{2.5}$/SrRuO$_3$ devices were fabricated on top of (111) and (001) oriented single crystalline SrTiO$_3$ substrates by pulsed laser deposition and electron-beam evaporation (see the Experimental Section). Depending on the substrate orientation, we call the memristive configurations SrFeO$_x$ (111) or (001) devices. Figure 2a schematically depicts a SrFeO$_x$ (111) device. The octahedral (FeO$_6$, orange) and tetrahedral (FeO$_4$, blue) layers are stacked alternatively along the in-plane (partially) direction of the thin film and propagate toward the surface normal at an angle of 55°. The 1D OVCs spontaneously order within the tetrahedral FeO$_4$ layers, as sketched in Figure 2b. As a result, OVCs connect the SrRuO$_3$ BE to the

![Figure 1.](image-url)  
Figure 1. a) Illustration of the reversible topotactic phase transition from BM-SrFeO$_{2.5}$ to PV-SrFeO$_3$. b,c) Schematic band diagrams of BM-SrFeO$_{2.5}$ (b) and PV-SrFeO$_3$ (c) with: $\Delta$, charge transfer energy; $U$, Coulomb repulsion energy; L, ligand hole; $\Delta_{eff}$, effective charge transfer energy as defined by the equation in the figure.
Au TE. The structural and microstructural characterization of the sample is presented in the supplementary information (see Figures S1 and S2, Supporting Information). As-prepared SrFeO$_x$ (111) memristive devices exhibit eightwise bipolar switching behavior (SET from HRS to LRS at positive bias applied to the Au electrode).

An exemplary $I-V$ curve of a fabricated SrFeO$_x$ (111) device is shown in Figure 2c. No initial forming step is necessary to obtain a stable resistive-switching behavior. Figure 2d shows the stack for SrFeO$_x$ (001) devices. The octahedral and tetrahedral layers are stacked along the in-plane direction of the thin film. Consequently, the OVCs in SrFeO$_x$ (001) devices order along the surface parallel within the tetrahedral layers (see Figure 2e). Contrary to the SrFeO$_x$ (111) devices, an electrical forming process is necessary to achieve resistive switching in (001) devices. The electroforming is performed by applying a voltage sweep in the range of $-3.0$ to $-5.0$ V with respect to the TE. Afterward, the device can be reversibly switched between an LRS and an HRS in an eightwise polarity manner (compare Figure 2f).

In order to clarify the resistive-switching phenomena in BM-SrFeO$_{2.5}$, we investigated the electronic structure of SrFeO$_x$ memristive devices in different defined resistance states (i.e., LRS and HRS) by imaging the devices across the O K-edge absorption region. After mechanical delamination of the top electrode, UV-PEEM was used to identify devices of interest (see Experimental section for details). Figure 3a shows a workfunction contrast secondary electron PEEM image of a SrFeO$_x$ (111) device in the LRS. Within the device area, a small region with increased brightness is visible (indicated by a white arrow), which we attribute to the conductive filament. This assumption can be justified by considering that the workfunction is sensitive to the average cation oxidation state and consequently to the oxygen-ion concentration.

We probed the region of interest using spatially resolved O K-edge XAS scans. The obtained O K-edge spectrum from this region is presented in Figure 3b together with a reference spectrum obtained from a device area without workfunction contrast. Interestingly, the O K-edge from the filament region shows a large difference in its spectral shape compared to the reference spectra. To qualitatively describe the absorption spectra, they can be subdivided into three different ranges, depending on the metal-oxygen hybridization, as following: 1) the pre-edge from $≈525$ to $533$ eV corresponds to Fe 3d-O 2p, 2) the raising edge around $≈535$ eV relates to the Sr 4d-O 2p hybridization, and 3) the broad features at $≈540$ eV stem from Fe 4sp-O 2p contributions.

Here, we note that the spectral features from ranges (2) and (3) show significant differences between the affected region and the reference; however, it is rather difficult to draw conclusions...
from those features due to their complex hybrid nature.\cite{43,44} Therefore, we will focus on the pre-edge (range 1) in the following analysis. The pre-edge peak position (peak B) from the reference spectrum is in good agreement with the spectrum of pure BM-SrFeO\(_{2.5}\) exhibiting a 3d\(^5\) ground state configuration as reported in the literature.\cite{30,33} The pre-edge from the filament region shows drastic changes in peak shape and position. Especially the feature from 526.5 to 532.6 eV is largely broadened due to an appearance of an additional peak (A) at an energy of 528.4 eV. This is well consistent with the O 2p ligand-hole configuration present in cubic PV-SrFeO\(_{3-\delta}\).\cite{31,34,42} We attribute these spectral changes to an increase of oxygen content in the SrFeO\(_x\) film from BM (\(x = 2.5\)) to PV (\(x = 3-\delta\)), which in turn leads to an increase in the covalency of the Fe 3d states due to the octahedral complex symmetry in PV-SrFeO\(_3\). Consequently, the ionic state of Fe is not well described by a 4\(^{+}\)(3d\(^4\)) configuration, but rather by a heavily mixed 3d\(^5\)L with 3d\(^4\) electronic configuration, where L denotes an electron-hole resulting from a charge transfer from the ligand O 2p orbitals to the Fe 3d ground states. The large occupation of L in the ground states leads to a metallic conductivity of PV-SrFeO\(_3\) because of a negative charge transfer energy.\cite{34,35} We thus conclude that the filament consists of a conductive PV-SrFeO\(_{3-\delta}\) phase while the surrounding area is composed of almost pure BM-SrFeO\(_{2.5}\). Only a small contribution of peak A can be observed in the reference spectra, which is also present in virgin devices (compare Figure S4, Supporting Information). To visualize the local confinement of the TPT, we subtracted the PEEM image measured at the photon energy of peak B from the corresponding image measured at peak A. The resulting difference image is displayed in Figure 3c and can be interpreted as a measure of the PV-SrFeO\(_{3-\delta}\) contribution. Only the filament region shows a significant PV-SrFeO\(_{3-\delta}\) contribution, meaning that the switching-induced TPT in SrFeO\(_x\) (111) devices is well confined within a small area (\(\approx 1 \mu m\)). As a control experiment we prepared a PV-SrFeO\(_{3-\delta}\) reference thin film by annealing a BM-SrFeO\(_{2.5}\) film in an oxygen atmosphere (Figure S1f, Supporting Information). By comparing the O K-edge spectra from the SrFeO\(_x\) (111) device within the filament region with the thermally prepared PV-SrFeO\(_{3-\delta}\) film, it was found that the peak shape and position are similar. We thus could confirm that during resistive switching in SrFeO\(_x\) (111) devices a TPT from insulating BM-SrFeO\(_{2.5}\) to conductive PV-SrFeO\(_{3-\delta}\) occurs. Here, it has be noted that the Fe L-edge XAS spectra from BM-SrFeO\(_{2.5}\) and thermally prepared PV-SrFeO\(_{3-\delta}\) film showed small spectral difference due to heavily mixed 3d\(^3\) and 3d\(^4\)
ground state configuration (see Figure S5, Supporting Information). Therefore, we only focused on the O K-edge spectromicroscopy investigation in this manuscript. In a second step we investigated another SrFeO$_x$ (111) device in the HRS (see Figure 3d–f). Within the device area, a small region with dark contrast could be identified (indicated by a white arrow), which we attribute to the filament in the HRS. The O K-edge spectra from this region reveal that there is only a small increase of peak A contribution (compare Figure 3e). The false-color peak difference image of the filament region is presented in Figure 3f. It is very clear that there is no significant contrast in the filament region, indicating a decrease of the octahedral population (i.e., change in oxygen stoichiometry from PV-SrFeO$_{3-\delta}$ to BM-SrFeO$_{3-\gamma}$) within the filament region. This illustrates, that the observed TPT is reversible in SrFeO$_x$ (111) memristive devices. On the basis of these spectroscopic insights we conclude that a field-driven local TPT is responsible for the resistance change in SrFeO$_x$ (111) memristive devices.

Likewise, we also investigated the switching in SrFeO$_x$ (001) memristive devices. Figure 3g shows a work function contrast secondary electron PEEM image of a SrFeO$_x$ (001) device in the LRS after TE delamination. Within the device area, a region with enhanced contrast is visible at the topmost left corner, which could be identified as an affected region with altered SrFeO$_x$ stoichiometry. The corresponding O K-edge absorption spectrum is presented in Figure 3h together with a reference spectrum extracted from a virgin device on the same sample. The spectrum from the affected region shows spectral characteristics matching the PV-SrFeO$_{3-\delta}$ phase such as the presence of peak A. To understand how the switching impacted the device, we imaged the device across the O K-edge absorption. The extracted pre-edge spectra from three regions of interest (indicated in Figure 3g) are shown in Figure 3i. Interestingly, the peak A contribution decreases along the diagonal of the device starting from the top left to the bottom right, while the intensity of peak B is increasing. As mentioned earlier, the intensity of peak A is associated with the O 2p ligand hole density and therefore is a measure of the octahedral symmetry present in cubic PV-SrFeO$_3$.[30,43] These observations reveal that the electrical treatment induced the formation of an oxygen-rich phase (i.e., PV-SrFeO$_{3-\delta}$), which is concentrated in the top left device region and gradually decreases across the device area. The recorded O K-edge XAS for devices switched into either the LRS or HRS state do not exhibit significant spectral changes, which indicates that the differences between the resistive states are small compared to the modifications appearing during the initial forming step.

The spectromicroscopic observations described above provide direct evidence for the TPT during resistive switching in SrFeO$_x$ devices. The resistive-switching-induced TPT in SrFeO$_x$ (111) devices (out-of-plane oriented OVCs) is confined within a small region (i.e., the conductive filament), while the TPT in SrFeO$_x$ (001) devices (in-plane oriented OVCs) spreads over a large area. In order to understand how the OVCs influence the TPT during the switching process, we consider the oxygen-ion migration process for both in-plane and out-of-plane oriented OVCs in the BM-SrFeO$_{3-\gamma}$ framework, which is presented in Figure 4a,d. As mentioned in the introduction, the inherently ordered OVCs in BM-SrFeO$_{3-\gamma}$ promote anisotropic oxygen-ion conduction. This means that OVCs serve as energetically favorable oxygen diffusion pathways within the tetrahedral FeO$_x$ layers. Mitra et al. investigated oxygen diffusion pathways in prototype BM-SrCoO$_{2.5}$ crystal structure by employing a first-principle calculation.[45] They found that the oxygen-ion diffusion within OVCs provides the easiest diffusion pathway with due to an activation energy of 0.62 eV, while diffusion perpendicular to OVCs requires a much higher activation energy of around 1.8 eV.

For SrFeO$_x$ (111) devices, the OVCs are rather aligned to the electrical field direction and create a pathway for oxygen-ion migration from BE to TE. When a positive bias is applied to the Au TE in a SrFeO$_x$ (111) device for a SET process, oxygen ions may drift from the SrRuO$_x$ BE into the BM-SrFeO$_{2.5}$ active layer along the OVCs and incorporate into the active layer, while changing some of the tetrahedral FeO$_x$ into octahedral FeO$_6$ sites. A schematic cross-sectional view of the filament structure in SrFeO$_x$ (111) devices is shown in Figure 4b. The fully connected conductive PV-SrFeO$_{3-\delta}$ filament drives the device resistance from the pristine state (or HRS) to the LRS, short-circuiting the bulk and the Schottky-type interfaces. Both, the Au/BM-SrFeO$_{2.5}$ and the BM-SrFeO$_{2.5}$/SrRuO$_x$ interface, are Schottky-type contacts due to the high work functions of Au and SrRuO$_x$ (the band alignment is schematically shown in Figure S6, Supporting Information). A subsequent negative bias at the TE causes the RESET process (i.e., LRS to HRS). During the RESET oxygen ions migrate back to the SrRuO$_x$ electrode interface, resulting in the local reduction of the PV-SrFeO$_{3-\delta}$ filament back to the original BM-SrFeO$_{2.5}$ phase at the vicinity of TE interface (Figure 4c), which is experimentally verified by the surface sensitive PEEM analysis (see Figure 3f). This observation confirms that the directional OVCs in the SrFeO$_x$ (111) device act as a local pathway for oxygen-ion migration from BE to TE and as such the filament is formed. That relatively large area (≈1 µm) PV-SrFeO$_{3-\delta}$ filament in Figure 3c might be due to high switching currents (≈2 mA). Moreover, SFO (111) devices are homogeneous and only small amount of external oxygen source is sufficient for making large PV-SrFeO$_{3-\delta}$ filaments. The confined reversible TPT together with the anisotropic fast ion conduction can explain the fast and controlled resistive switching in SrFeO$_x$ (111) device, which we reported previously (compare ref. [37]).

In contrast to the SrFeO$_x$ (111) devices, the direction of the electrical field in the SrFeO$_x$ (001) memristive devices is perpendicular to the in-plane oriented OVCs. Consequently, the electric field driven TPT in SrFeO$_x$ (001) devices spreads over a large area due to the fast oxygen-ion diffusion within in-plane ordered OVCs (see Figure 4d,e), which is well consistent with our spectromicroscopic analysis for SrFeO$_x$ (001) devices. Furthermore, electric field driven oxygen-ion migration between the TE and BE is hindered due to the presence of alternating octahedral and tetrahedral layers stacked along the out-of-plane direction. In consequence, an initial forming process at higher electric fields is necessary to obtain a resistive-switching behavior in SrFeO$_x$ (001) devices. During the initial forming process, when a sufficient negative bias is applied to the Au TE, oxygen species from the atmosphere (e.g., O$_2$ or H$_2$O) can be incorporated into the active switching layer and then drift toward the BE interface. This is in
agreement with recent observation that oxygen exchange processes can take place between the surrounding atmosphere and the switching layer during operation. The incorporated oxygen ions migrate toward the SrRuO$_3$ BE due to the negative bias at the TE, while partly changing the tetrahedral layers to octahedral layers in the BM-SrFeO$_{2.5}$ structure. Consequently, an oxygen-rich conductive PV-SrFeO$_{3-\delta}$ phase is formed presumably at bottom SrFeO$_x$/SrRuO$_3$ interface, which results in a decrease of the Schottky barrier height and width, which turns the device resistance from the pristine insulating state to the (comparably conductive) HRS. This forming induced PV-SrFeO$_{3-\delta}$ region is experimentally observed (see Figure 2a). A schematic illustration of the proposed field driven TPT in SrFeO$_x$ (001) devices is presented in Figure 4e. By applying a positive bias to the TE (SET process), oxygen ions drift from the bottom to the top interface, resulting in an oxygen-rich PV-SrFeO$_{3-\delta}$ phase at the top interface. This implies that the switching process and the corresponding TPT take place at the Au TE interface. However, we have only been able to present the forming process for SrFeO$_x$ (001) devices and could not identify a systematic spectral trend between cells in LRS and HRS. This might be due to the large spectral variations throughout the cell area after the forming process. Based on the switching polarity of SrFeO$_x$ (001) devices, we suggest that the resistive switching in the SrFeO$_x$ (001) devices might be due to reversible modulation of the interfacial oxygen stoichiometry at TE interface, which leads to Schottky barrier height and width variation during the set and reset operations.

In conclusion, by using X-ray absorption spectromicroscopy, we have successfully verified the switching mechanism in BM-SrFeO$_{2.5}$ memristive devices. In contrast to many TMO-based ReRAM devices such as SrTiO$_{3-x}$, TiO$_{2-x}$, HfO$_{2-x}$, and Ta$_2$O$_{5-x}$ resistive switching in BM-SrFeO$_{2.5}$ is not caused by the formation and rupture of an oxygen vacancy rich filament, but rather by a reversible TPT between an insulating BM-SrFeO$_{2.5}$ and a conductive PV-SrFeO$_{3-\delta}$ phase. Tailored OVCs connecting the BE to the TE in the inherent structure of as-prepared SrFeO$_x$ (111) thin films promote a localized TPT, resulting in a confined filament structure. Conversely, SrFeO$_x$ (001) devices exhibit a nonlocalized phase transition due to the energetically favored oxygen-ion diffusion within the in-plane oriented OVCs. These findings demonstrated an opportunity to implement resistive switching within the framework of TPT and establish alignment of favorable axis for oxygen-ion transport as a versatile route for performance optimization of memristive devices.

**Experimental Section**

**Device Fabrication:** A 30 nm thick epitaxial SrRuO$_3$ BE was deposited on a single crystalline SrTiO$_3$ substrate (Shinkosha, Japan) by pulsed laser deposition using a KrF excimer laser ($\lambda = 248$ nm) with a repetition rate of 4 Hz and a spot size of 2 mm$^2$ at a target-to-substrate distance of
44 mm (substrate temperature of 640 °C, the laser fluence was 2.5 J cm\(^{-2}\) and oxygen atmosphere of 0.1 mbar). Then, a 20 nm thick BM-SrFeO\(_{2.5}\) thin film was deposited on the top of the SrRuO\(_3\) layer with a repetition rate of 4 Hz and a spot size of 2 mm\(^2\) at a target-to-substrate distance of 44 mm (substrate temperature of 640 °C, the laser fluence was 2.0 J cm\(^{-2}\) and oxygen atmosphere of 10\(^{-5}\) mbar). The film growth was monitored using reflection high-energy electron diffraction. Afterward a 30 nm of Au TE was deposited using electron beam evaporation and patterned using optical lithography and ion beam etching.

**Electrical Characterization:** For electrical characterization, the Au TE was contacted with tungsten whisker probes. The epitaxial SrRuO\(_3\) layer served as an electrically grounded bottom electrode and was contacted by wire bonding. The I–V characteristics were measured using a Keithley 2611A SourceMeter. After the forming process or initial cycle, some of the cells were kept in the LRS and others were switched back into the HRS for subsequent spectromicroscopic analysis.

**Top Electrode Delamination:** For spectromicroscopic analysis, the Au TE was mechanically delaminated under ultrahigh vacuum conditions using an adhesive copper tape after electron beam deposition of a homogeneous 30 nm Au layer onto the entire sample. The delaminated sample was transferred into the PEEM chamber under ultrahigh vacuum conditions.

**Spectromicroscopy:** All spectromicroscopy experiments were performed at the NanoESCA beamline at Elettra Synchrotron Laboratory (Trieste, Italy).[2] The secondary electron images were acquired by PEEM using a high-pressure mercury lamp as excitation source. For O K-edge absorption spectra, various series of images were taken at increasing photon energies, using a step size of 0.2 eV. All measurements were performed while keeping the sample at room temperature with an overall energy resolution of 120 meV and spatial resolution of 100 nm. Extracted XAS spectra from the region of interests were background corrected by a linear fit of the pre-edge and subsequent normalization by fitting a third-order polynomial to the postedge using the ATHENA software.[13]

**Supporting Information**

Supporting Information is available from the Wiley Online Library or from the author.

**Acknowledgements**

V.R.N. and T.H. contributed equally to this work. This work was supported by the Basic Science Research Program through National Research Foundation of Korea (NRF) grants funded by the Ministry of Education, Science, and Technology (NRF-2016R1A2B4015911), M. K. by NRF-2017M3D1A1040688. T.H., C.B., and R.D. gratefully acknowledge funding from the DFG (German Science Foundation) within the collaborative research center SFB 917 “Nanoswitches” and from the W2/W3 program of the Helmholtz association. C.B. received funding from the European Union’s Horizon 2020 research and innovation program under the Marie Sklodowska-Curie Grant Agreement No. 796142. V.R.N., T.H., C.B., and R.D. conceived and designed the experiments. V.R.N. and T.H. fabricated the samples and performed the electrical conductivity measurements. V.R.N., T.H., M.J., G.Z., and V.F. performed the spectromicroscopic experiments. V.R.N., T.H., C.B., C.U.J., and R.D. evaluated and interpreted the results. C.B., M.K., C.M.S., R.W., C.U.J., and R.D. supervised the research. V.R.N., T.H., and C.B. wrote the manuscript supported by important discussions with C.U.J. and R.D. and contributions from all authors.

**Conflict of Interest**

The authors declare no conflict of interest.

**Keywords**

brownmillerite, resistive switching, topotactic phase transition, XPEEM

Received: May 28, 2019
Revised: July 26, 2019
Published online: August 22, 2019
